

TECHNICAL BULLETIN

FLASHBOND™ UV-5608DC

UV/LED CURE EPOXY ADHESIVE

FLASHBOND™ UV-5608DC is an innovative light cure epoxy adhesive. It has unique features that allow for fast processing and fixturing of parts. Once the adhesive has been activated with UV light, it has set open time that allows for assembly of parts. The product continues to cure at room temperature or rapidly cures when exposed to low temperature heat. The cured product exhibits low shrinkage and excellent thermal, water and chemical resistance. Typical applications include bonding of optics, connectors, fibers, lenses, prisms and other electronic components where low shrinkage and low outgassing are required.

TYPICAL HANDLING PROPERTIES:

Chemical Type	Cationic Epoxy
Viscosity at 25°C, cps	4000-7000
Specific Gravity, 25°C	1.12

Recommended Curing Conditions:

Pre-activated @ 100-150 mW/cm², measured @ 405 nm or 365 nm for 6-8 seconds resulting in an open time of 45-60 seconds. Full cure will follow in 24-48 hrs.

For full cure (no open time), increase cure time to 20-30 seconds or increase intensity to 250-400 mW/cm² and cure for 5-8 seconds/

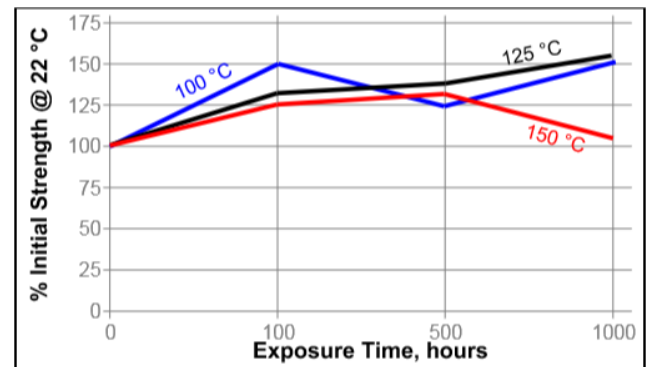
TYPICAL CURED PROPERTIES AFTER RECOMMENDED CURE:

(Tested @ 25°C unless otherwise indicated)

Color	Translucent
Hardness, Shore D	75
Water Absorption (24 hr @ RT), %	0.15
Linear Shrinkage, %	0.8
Elongation at break, %	7.6
Lap Shear Strength Al/Al, psi	2500
Tensile Strength, psi	3000
Service Temperature range, °C	-55 to 150
Glass Transition Temperature, °C	81
Coefficient of Linear Thermal Expansion, 10 ⁻⁶ /°C	
Below Tg	59
Above Tg	>120
Dielectric Strength, Volts/mil	420
Dielectric Constant at 1 kHz	4.14
Dissipation Factor at 1 kHz	0.02
Volume Resistivity (ohm-cm)	1.0x10 ¹⁴

Heat aging

Aged at temperature indicated and tested at 25°C



Strength Testing

Strength build up over time and tested at 25°C

